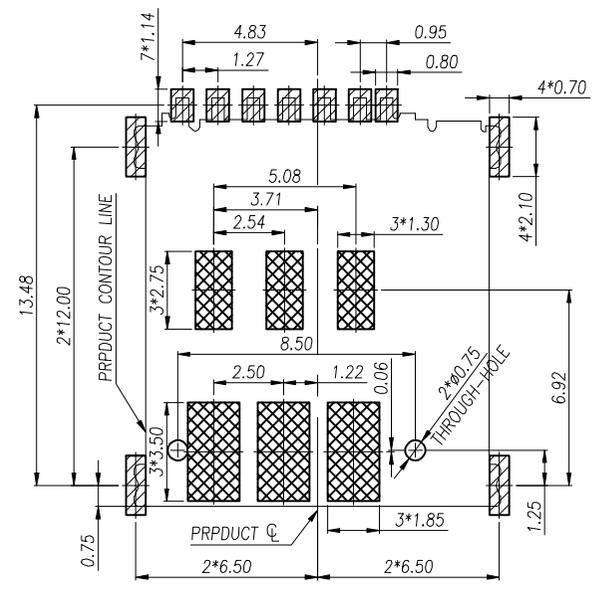
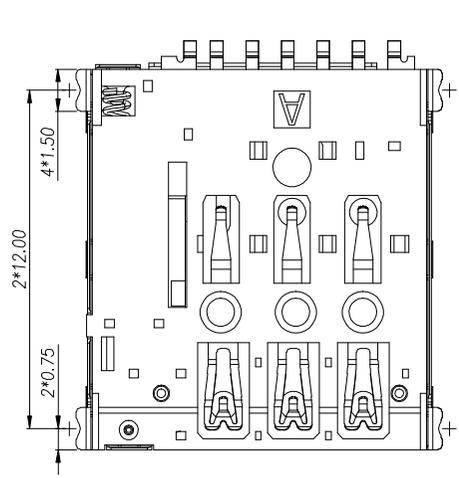
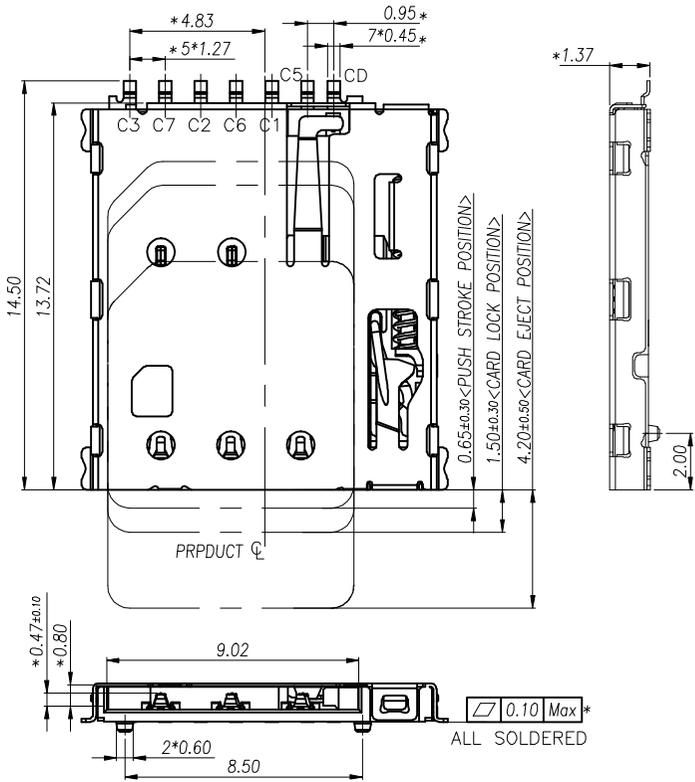


PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE

REV.	Q'TY	ECN. NO.	APR.	DATE
A		FIRST RELEASE	Lin R	230521

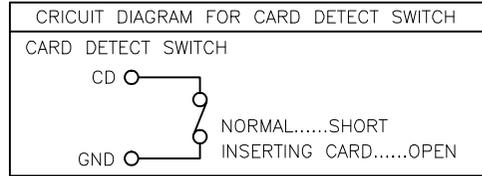


RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
RECOMMENDED MATAL MASK T=0.12mm

- SMT SOLDER AREA
- NO PATTERN AND VIA HOLE IN HTIS AREA

- NOTES:
- MATERIAL:
HOUSING: High Temperature Thermoplastic
Terminal:Copper Alloy
Shell: Stainless Steel
 - PLATING:
Terminal:50u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA
Shell:30u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA
 - TECHNICAL SPECIALITY:
RATED VOLTAGE: 30V AC MAX.
CURRENT RATING: 0.5A MAX.
INSULATION RESISTANCE:1000MΩ MIN
CONTACT REISTANCE:50mΩ MAX
WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES
OPERATING TEMPERATURE:
-25℃~+85℃ Humidity 80% R.H MAX
 - DIMENSIONS WITH MARK * MUST BE MEASURE BY QC AND IQC

PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
CD	Detect Switch
C5	GND
C6	VPP
C7	I/O



3D VIEW

DIMENSION IN mm		TOLERANCE UNLESS OTHERWISE SPECIFIED		APR.		TITLE: 自弹式 NanoSIM卡卡座	
.X±0.35	.X'± 5'			CHK.		DWG NO. ZX-NSIM-481.37J	
.XX±0.25	.X'± 3'			DRA.		PROV.	
.XXX±0.15	.XX'± 1'			SIZE A4		SCALE 4:1 SHEET 1/2 REV. A	

兆星精密电子 (深圳) 有限公司